

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	$R_{thJS}$		K/W
BCR142		$\leq 240$	
BCR142W		$\leq 105$	

**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

**DC Characteristics**

Collector-emitter breakdown voltage $I_C = 100 \mu\text{A}, I_B = 0$	$V_{(BR)CEO}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10 \mu\text{A}, I_E = 0$	$V_{(BR)CBO}$	50	-	-	
Collector-base cutoff current $V_{CB} = 40 \text{ V}, I_E = 0$	$I_{CBO}$	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 10 \text{ V}, I_C = 0$	$I_{EBO}$	-	-	227	$\mu\text{A}$
DC current gain <sup>2)</sup> $I_C = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	$h_{FE}$	70	-	-	-
Collector-emitter saturation voltage <sup>2)</sup> $I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$	$V_{CEsat}$	-	-	0.3	V
Input off voltage $I_C = 100 \mu\text{A}, V_{CE} = 5 \text{ V}$	$V_{i(off)}$	0.5	-	1.2	
Input on voltage $I_C = 2 \text{ mA}, V_{CE} = 0.3 \text{ V}$	$V_{i(on)}$	0.8	-	2.5	
Input resistor	$R_1$	15	22	29	$k\Omega$
Resistor ratio	$R_1/R_2$	0.42	0.47	0.52	-

**AC Characteristics**

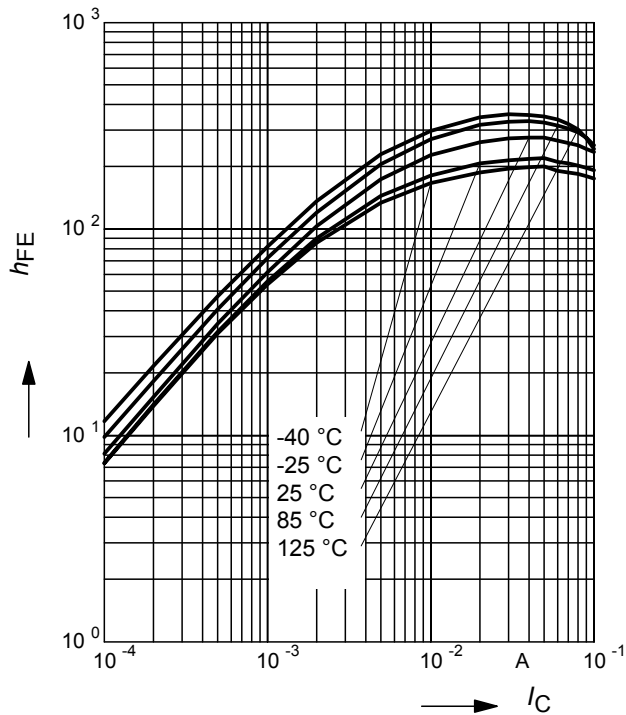
Transition frequency $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}, f = 100 \text{ MHz}$	$f_T$	-	150	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	$C_{cb}$	-	3	-	pF

<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note AN077 (Thermal Resistance Calculation)

<sup>2)</sup>Pulse test:  $t < 300 \mu\text{s}$ ;  $D < 2\%$

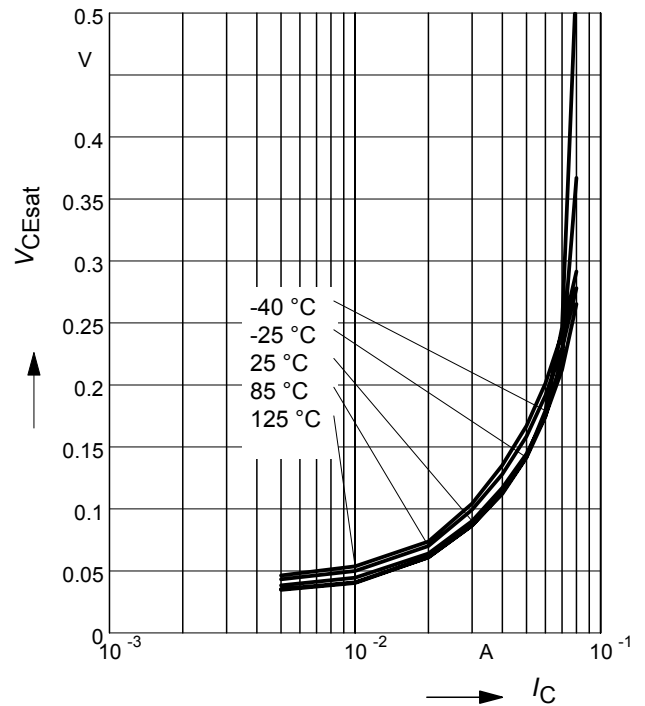
### DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 5V$  (common emitter configuration)



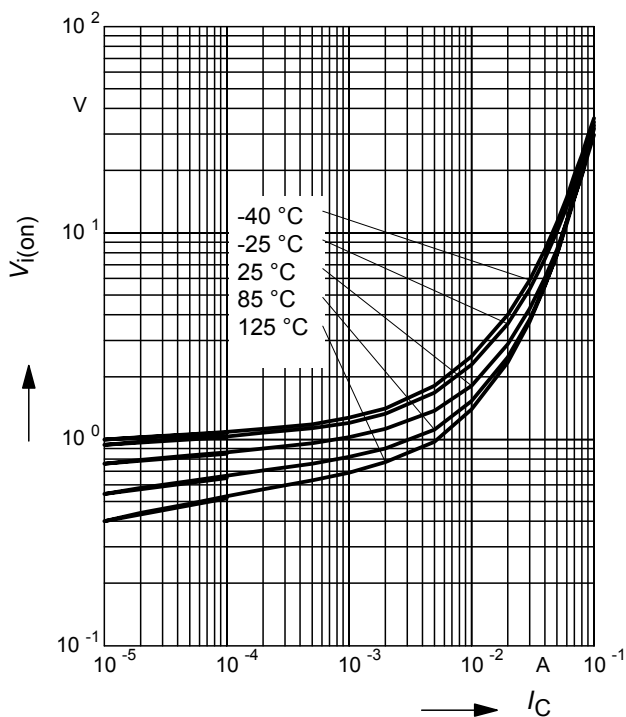
### Collector-emitter saturation voltage

$V_{CEsat} = f(I_C), I_C/I_B = 20$



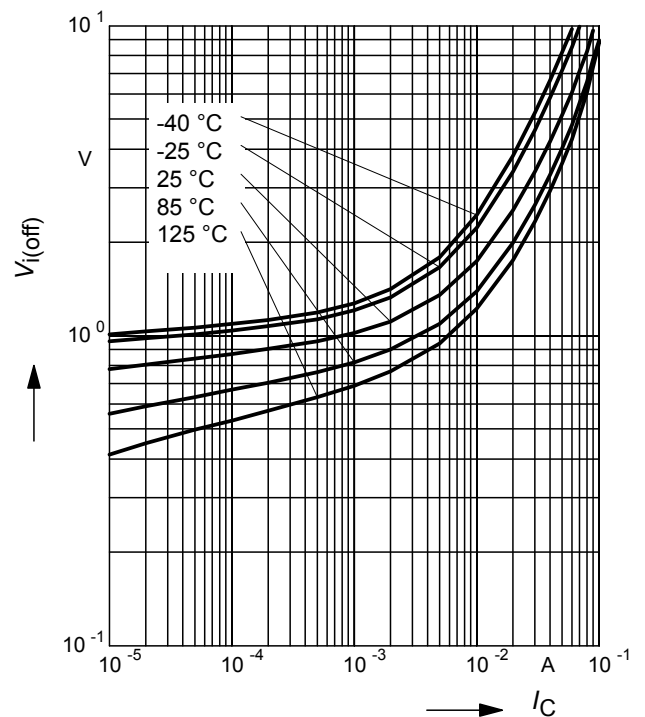
### Input on Voltage $V_{i(on)} = f(I_C)$

$V_{CE} = 0.3V$  (common emitter configuration)



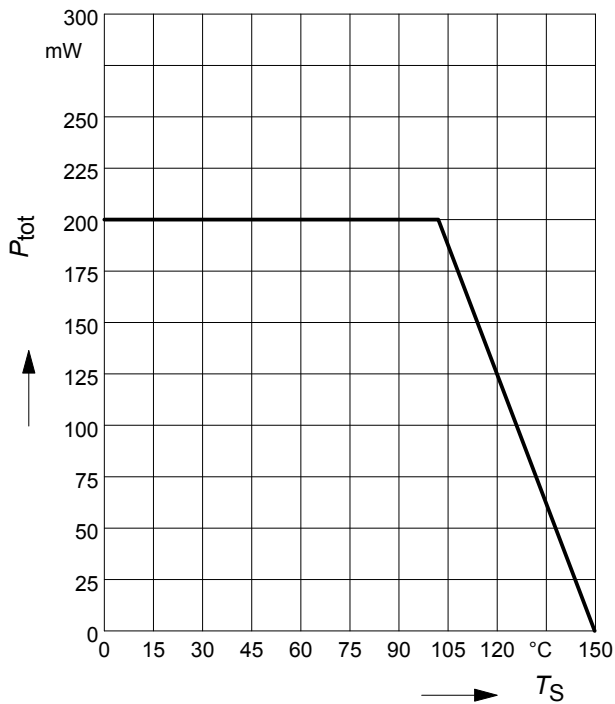
### Input off voltage $V_{i(off)} = f(I_C)$

$V_{CE} = 5V$  (common emitter configuration)



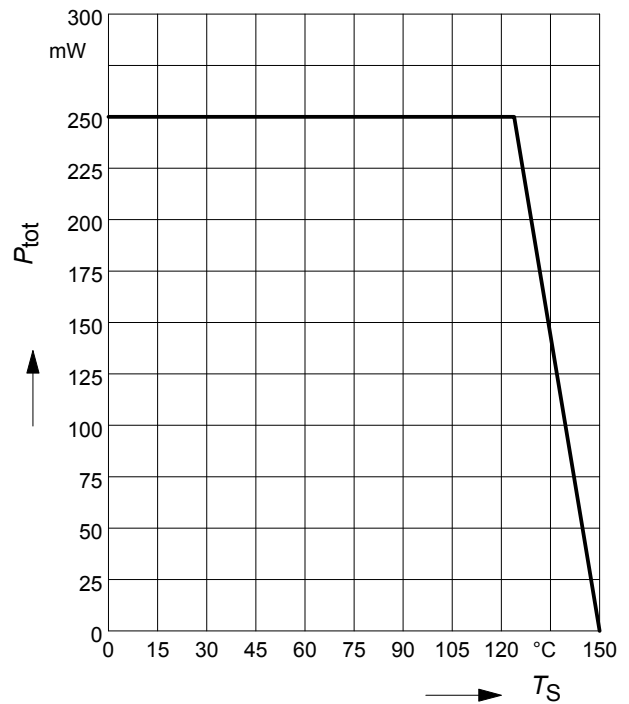
Total power dissipation  $P_{\text{tot}} = f(T_S)$

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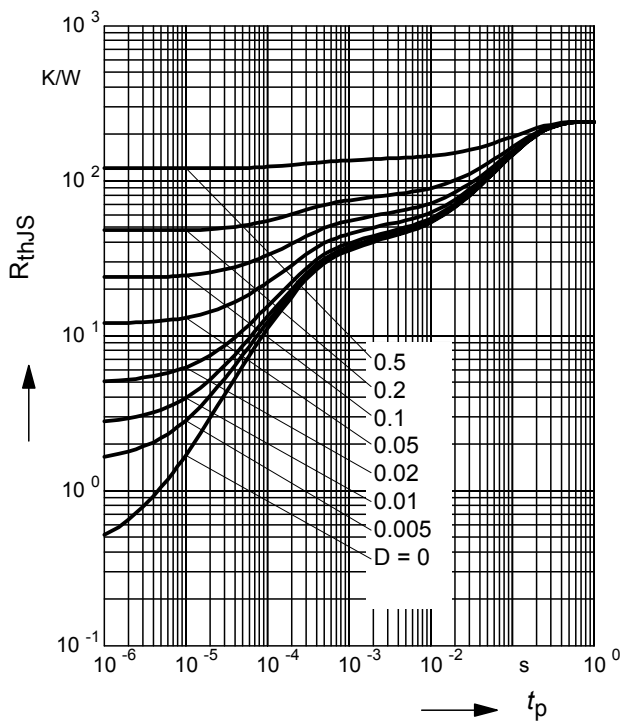
Total power dissipation  $P_{\text{tot}} = f(T_S)$

BCR142W



Permissible Pulse Load  $R_{\text{thJS}} = f(t_p)$

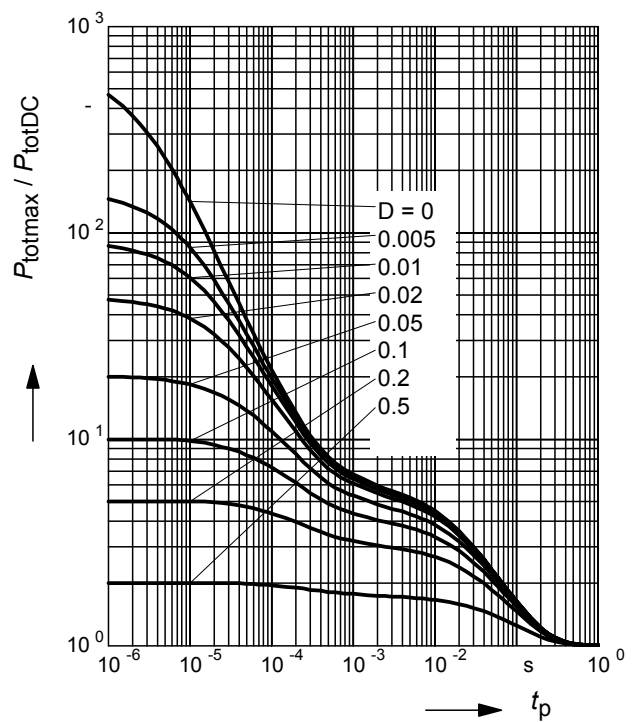
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Permissible Pulse Load

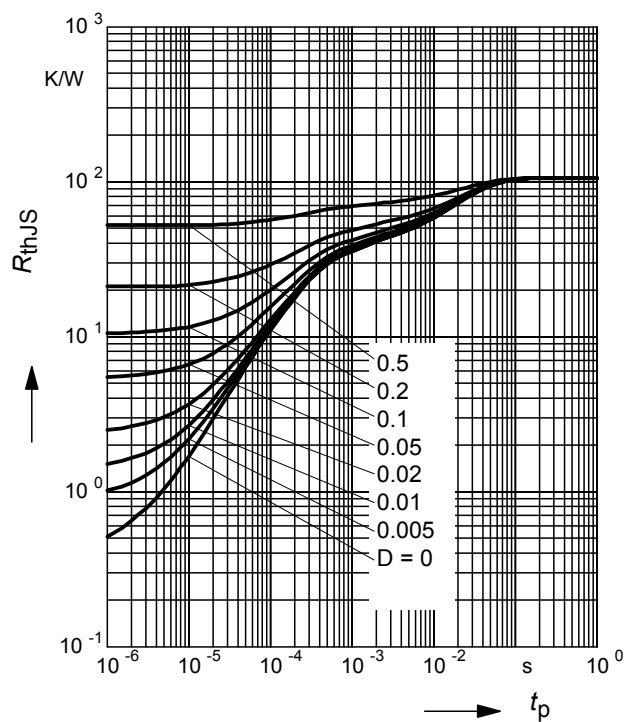
$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$

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# Permissible Puls Load $R_{thJS} = f(t_p)$

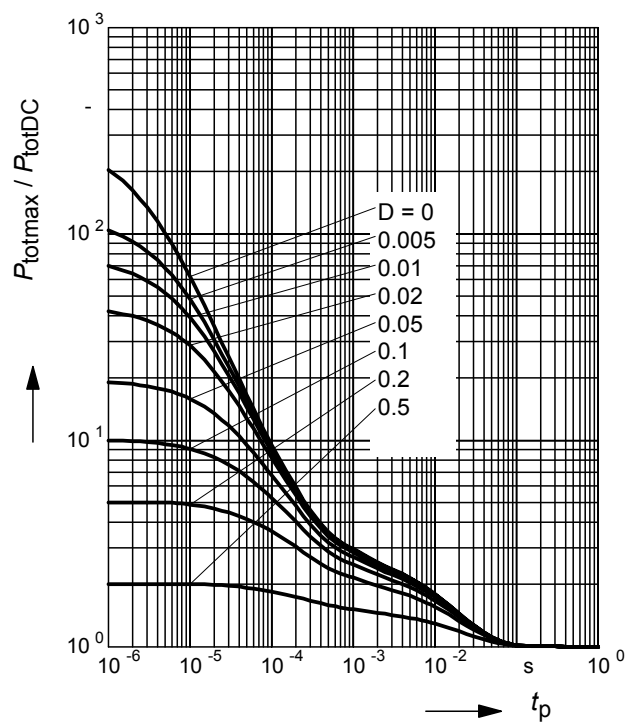
BCR142W



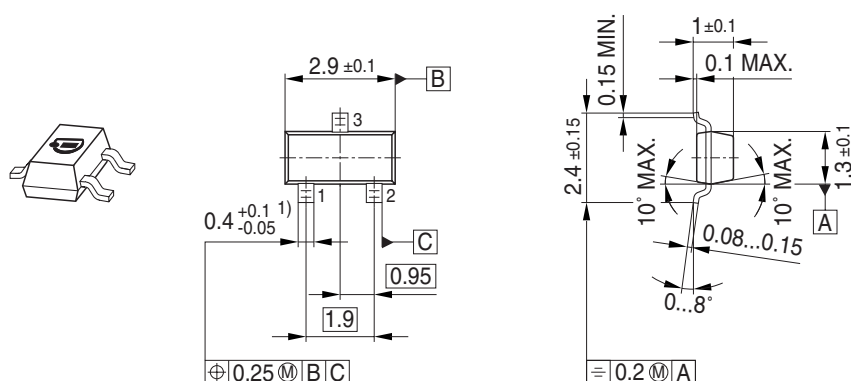
# Permissible Pulse Load

$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR142W

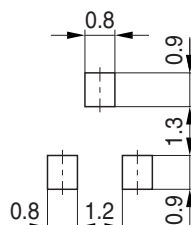


## Package Outline

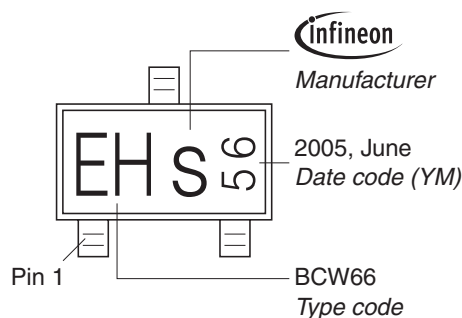


1) Lead width can be 0.6 max. in dambar area

## Foot Print

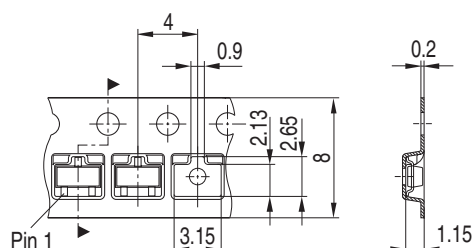


## Marking Layout (Example)

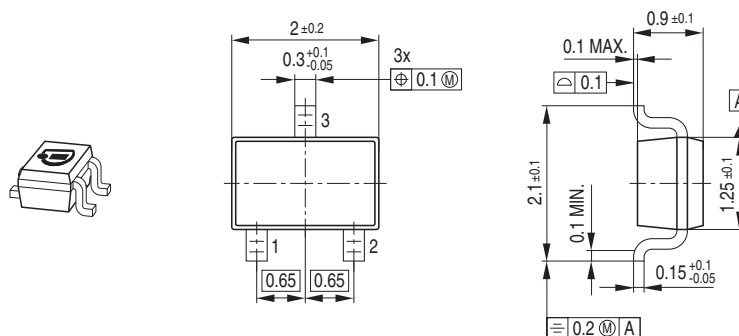


## Standard Packing

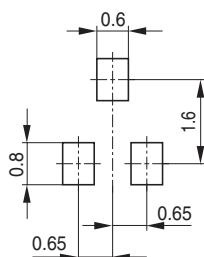
Reel ø180 mm = 3.000 Pieces/Reel  
Reel ø330 mm = 10.000 Pieces/Reel



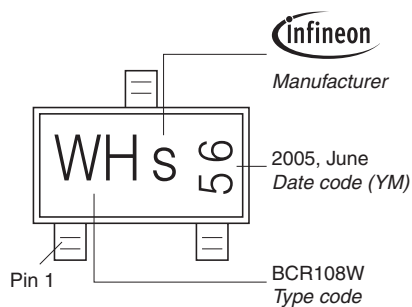
## Package Outline



## Foot Print

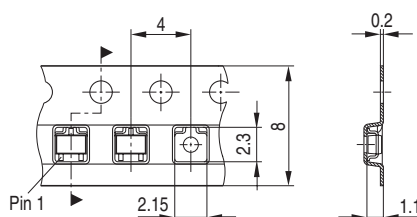


## Marking Layout (Example)



## Standard Packing

Reel  $\varnothing 180$  mm = 3.000 Pieces/Reel  
 Reel  $\varnothing 330$  mm = 10.000 Pieces/Reel



**Edition 2009-11-16**

**Published by  
Infineon Technologies AG  
81726 Munich, Germany**

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